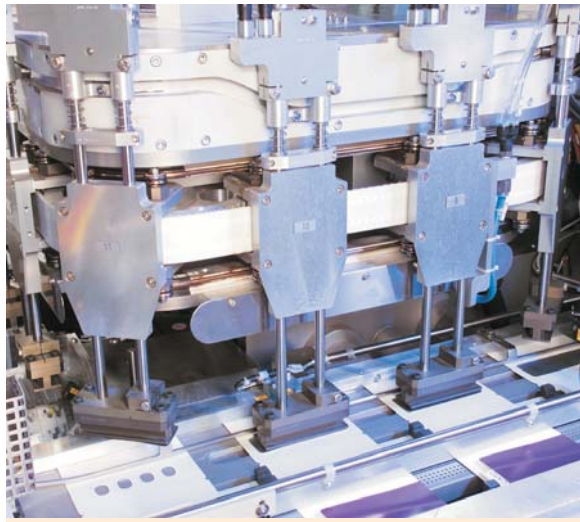


Hotmelt and sealing lacquer

Two processes for the firm joining of blanks and package components.

With the choice between hotmelt and sealing lacquer, the markets are bustling with a variety of trends. Low-cost hotmelt glue processes are preferred in Europe and on the Asian market. In contrast in the USA product-secure childproof packs are manufactured both by the sealing-lacquer process and by the hotmelt-glue process. Höfliger offers perfected modular technology for both of these processes. Depending on requirement, Höfliger develops tailor-cut additional aggregates, also for Wallet machines, such as blister folding machines for double blisters or buffer modules for the individual package components.



Handling systems for processes at maximum speed rates

For the firm union of package component and carrier board, the first option is to glue the flaps with hotmelt. The glue rope is applied in an inline process. Each gluing process is followed by the feeding and pressing-on of a package component or by a folding operation.

This reliable method proved to be correct, faster and more cost-efficient for many projects.

Completely different possibilities are provided by the heat-sealing lacquering process. The surfaces of the Wallet blanks, pre-coated with sealing lacquer, are brought together and heated in a sealing unit. The required sealing pressure is applied for a firm bonding that cannot be undone without destroying the package.



Co-travelling sealing station for sealing lacquer applications in Wallet packs



Process for the production of Wallet packages with glued-in blister card

